# Surface Mount Chip Resistors

## Style CS

### **General Specifications**

• Resistance: 50 and 100  $\Omega$  standard

 Resistive Tolerance: ±5% Standard (2% Available).

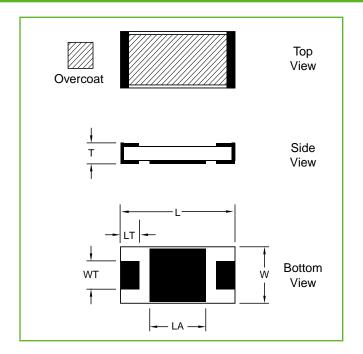
• Operating Temp Range: -55 to +150°C

Temperature Coefficient: ±150 ppm/°C

• Resistive Elements: Proprietary film.

• Substrate Material: Aluminum Nitride.

Terminals: Silver over NickelReliability: MIL-PRF-55342

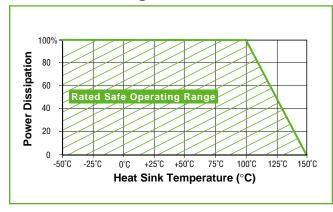


ATC Part Number	W	L	Т	WT	LT	LA	Capacitance	Power Max*
	±.010	±.010	±.005	±.005	±.005	±.005	(pF)	(Watts)
CS12010T0100G	.100	.200	.040	.090	.030	.095	.95 pF	10
CS12525T0100G	.245	.245	.040	.120	.040	.110	1.85 pF	20
CS13725T0100G	.250	.375	.040	.120	.050	.195	3.0 pF	30
CS13737T0100G	.370	.370	.040	.360	.050	.195	3.5 pF	40

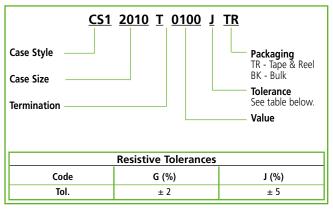
<sup>\*</sup> Test Condition: Chip soldered to a via patch on a 30-mil-thick Rogers RO4350 board; Land surfaces at 100° C; maximum rated power applied.

Specification: The resistance of the film shall change no more than 0.5% during and after a 1000-hr. Burn-in per Mil-PRF-55342

#### **Power Derating**



#### **ATC Part Number Code**



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